

CURRENT LISTING OF CLAIMS

This listing of claims replaces all previous listing of claims. Kindly amend the claims as follows:

1. (currently amended) An apparatus for attaching a leaded component to a substrate, comprising:

a mounting plate having a base portion, a first side wall extending from a first side of the base portion in a first direction, a second side wall extending in the first direction from a second side of the base portion that is axially aligned to the first side of the base portion, and at least one mounting flange extending from the first side wall and away from the base portion and at least one mounting flange extending from the second side wall and away from the base portion and at least one hole extending down at least one of the first side wall and second side wall through to the base portion of the mounting plate through which to pass a lead of a component; and

a heat sink, separate and distinct from the mounting plate, that is removably secured relative to the mounting plate by the mounting flanges.

2. (cancelled).
3. (original) The apparatus according to claim 1, wherein the mounting flanges secures the component to the mounting plate.
4. (cancelled).

5. (previously presented) The apparatus according to claim 1, wherein the mounting flanges include holes for a fastener.
6. (previously presented) The apparatus according to claim 5, wherein the heat sink includes holes for the fastener to fasten the heat sink to the mounting flanges.
7. (original) The apparatus according to claim 6, wherein the fastener includes one of a screw, a rivet, and a bolt.
8. (original) The apparatus according to claim 1, further comprising a thermal interface material adjoining a lower surface of the heat sink.
9. (previously presented) The apparatus according to claim 8, wherein the lower surface of the base portion of the mounting plate is fastened to a substrate and the heat sink is mounted to the mounting flanges and the lower surface of the heat sink is in thermal communication with an upper surface of the component through the thermal interface material.
10. (previously presented) The apparatus according to claim 9, wherein the side walls and flanges partially surround the component.
11. (original) The apparatus according to claim 9, wherein the mounting plate is electrically insulated.

12. (cancelled).

13. (cancelled).

14. (cancelled).

15. (cancelled).

16. (previously presented) The apparatus according to claim 1, wherein the base portion of the mounting plate includes fewer holes than the number of leads of the component.

17. (cancelled).

18. (original) The apparatus according to claim 1, wherein the component is a through hole mounted component.

19. – 26. (cancelled).